



Figure 7.6 A typical processing sequence with schematic illustrations of the resulting structures

a very bad quality and the defects can lead to wafer fracture during processing [68]. For this reason, about ten microns are etched off from each face in alkaline or acid solutions. The wafers, in Teflon cassettes, are immersed in tanks containing the solution under temperature and composition control. Alkaline etches are preferred to acid solutions due to considerations of waste disposal.